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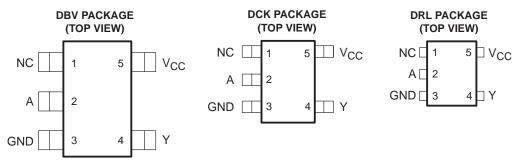
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Jameco Part Number 1384368

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- Operating Range of 2 V to 5.5 V
- Max t_{pd} of 6.5 ns at 5 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±8-mA Output Drive at 5 V

- Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- Latch-Up Performance Exceeds 250 mA Per JESD 17



NC - No internal connection

See mechanical drawings for dimensions.

description/ordering information

The SN74AHC1G04 contains one inverter gate. The device performs the Boolean function $Y = \overline{A}$.

TA	PACKAGE	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]						
	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G04DBVR	4.04						
		Reel of 250	SN74AHC1G04DBVT	A04_						
–40°C to 85°C	00T (00 70) DOK	Reel of 3000	SN74AHC1G04DCKR	10						
	SOT (SC-70) – DCK	Reel of 250	SN74AHC1G04DCKT	AC_						
	SOT (SOT-553) – DRL	Reel of 4000	SN74AHC1G04DRLR	AC_						

ORDERING INFORMATION

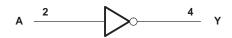
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	$\begin{array}{c} -0.5 \mbox{ V to 7 V} \\ -0.5 \mbox{ V to V}_{CC} + 0.5 \mbox{ V} \\ -20 \mbox{ mA} \\ \pm 20 \mbox{ mA} \\ \pm 25 \mbox{ mA} \\ \pm 50 \mbox{ mA} \\ 206^{\circ}\mbox{ C/W} \\ 252^{\circ}\mbox{ C/W} \end{array}$
DCK package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
		$V_{CC} = 2 V$	1.5		
ViH	High-level input voltage	$V_{CC} = 3 V$	2.1		V
		$V_{CC} = 5.5 V$	3.85		
		$V_{CC} = 2 V$		0.5	
\vee_{IL}	Low-level input voltage V _{CC} = 3 V			0.9	V
		$V_{CC} = 5.5 V$		1.65	
VI	Input voltage		0	5.5	V
VO	Output voltage		0	VCC	V
		$V_{CC} = 2 V$		-50	μΑ
IОН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	
		V_{CC} = 5 V ± 0.5 V		-8	mA
		$V_{CC} = 2 V$		50	μΑ
lol	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	~^^
		V_{CC} = 5 V ± 0.5 V		8	mA
A #/ A	$V_{CC} = 3.3 V \pm 0.3$			100	n o//
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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			T,	₄ = 25°C	;			
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		
	I _{OH} = -50 μA	3 V	2.9	3		2.9		
VOH		4.5 V	4.4	4.5		4.4		v
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1		0.1	
VOL		4.5 V			0.1		0.1	V
01	I _{OL} = 4 mA	3 V			0.36		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.44	
l	$V_{I} = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			1		10	μA
Ci	$V_{I} = V_{CC}$ or GND	5 V		2	10		10	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		FROM	то	LOAD	Τ ₄	λ = 25°C	;			
PA	ARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
	^t PLH	•	N.	0 45 - 5		5	7.1	1	8.5	
	^t PHL	A	Ŷ	C _L = 15 pF		5	7.1	1	8.5	ns
	^t PLH	٨	v	$C_{1} = 50 \text{ pF}$		7.5	10.6	1	12	20
	^t PHL	A	T	CL = 50 pF		7.5	10.6	1	12	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

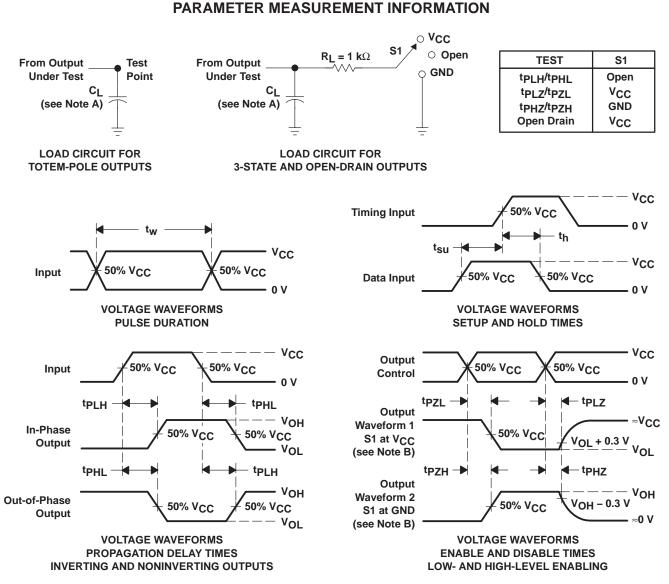
Γ	DADAMETED	FROM	то	LOAD	Т	λ = 25°C	;			
	PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
ſ	^t PLH		X	0 45 - 5		3.8	5.5	1	6.5	
ſ	^t PHL	A	Ŷ	C _L = 15 pF		3.8	5.5	1	6.5	ns
ſ	^t PLH	٨	V			5.3	7.5	1	8.5	
	^t PHL	A	Y	Y C _L = 50 pF		5.3	7.5	1	8.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	12	pF



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NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHC1G04DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G04DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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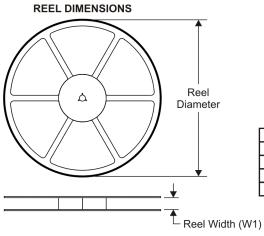
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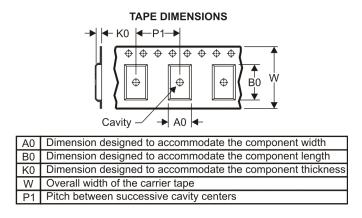
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G04DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G04DBVT	SOT-23	DBV	5	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G04DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G04DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G04DCKT	SC70	DCK	5	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G04DCKT	SC70	DCK	5	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G04DRLR	SOT	DRL	5	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3



PACKAGE MATERIALS INFORMATION

31-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G04DBVR	SOT-23	DBV	5	3000	205.0	200.0	33.0
SN74AHC1G04DBVT	SOT-23	DBV	5	250	205.0	200.0	33.0
SN74AHC1G04DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74AHC1G04DCKR	SC70	DCK	5	3000	205.0	200.0	33.0
SN74AHC1G04DCKT	SC70	DCK	5	250	202.0	201.0	28.0
SN74AHC1G04DCKT	SC70	DCK	5	250	205.0	200.0	33.0
SN74AHC1G04DRLR	SOT	DRL	5	4000	202.0	201.0	28.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.



DRL (R-PDSO-N5)

PLASTIC SMALL OUTLINE



NOTES:

All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. Α. B. This drawing is subject to change without notice.

🖄 Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.





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